

Amendments to the Claims are as follows:

1. (Currently Amended) A circuit device comprising:
  - a substrate;
  - a semiconductor chip mounted on the substrate; and
  - a sealing layer for sealing the semiconductor chip so as to coverthe semiconductor chipit, wherein  
the sealing layer comprises a silicone-based material.
2. (Currently Amended) A circuit device according to Claim 1, wherein  
atthe thixotropic index of the silicone-based material is from 2 to 6.
3. (Currently Amended) A circuit device according to Claim 1, wherein  
anthe elastic coefficient of the silicone-based material is from 1 to 50 MPa.
4. (Original) A circuit device according to Claim 1, further comprising a  
shielding member arranged on the substrate so as to cover the sealing layer  
on the substrate, wherein the shielding member and the substrate are  
soldered to each other.
5. (Currently Amended) A method for making a circuit device,  
comprising:~~the steps of:~~
  - mounting a semiconductor chip on a substrate; and
  - forming a sealing layer so as to cover the semiconductor chip,wherein  
the sealing layer comprises a silicone-based material.
6. (Currently Amended) A method for making a circuit device  
according to Claim 5, wherein atthe thixotropic index of the silicone-based  
material is from 2 to 6.
7. (Currently Amended) A method for making a circuit device  
according to Claim 5, wherein anthe elastic coefficient of the silicone-based  
material is from 1 to 50 MPa.

8. (Currently Amended) A method for making a circuit device according to Claim 5, wherein the circuit device comprises a shielding member arranged on the substrate so as to cover the sealing layer on the substrate, and the method further comprises ~~the step of soldering the~~ shielding member and the substrate to each other.